

Discription

The HAOZ8211DI-12 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



DFN1006-2L

Features

★ Transient protection for high-speed data lines IEC 61000-4-2(ESD) ±8kV (Contact) ±15kV (Air)

IEC 61000-4-4(EFT) 40A (5/50 ns)

★ Peak power dissipation: 150W (8/20us)

★ Working voltages: 12V

★ Ultra-small package (1.0mmx0.6mmx0.5mm)

★ Protects one data, control line

★ Low capacitance: 45pF (Typical)

★ Low clamping voltage

★ Low leakage current



Circuit Diagram

Orderingin formation

Product ID	Pack	Qty(PCS)
HAOZ8211DI-12	DFN1006-2L	10000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 μ s)	150	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-55 to +150	°C
T_j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±15 ±8	KV
	IEC61000-4-4 (EFT)	40	Α



Electrical Characteristics Ratings at 25°C

Symbol	Parameter	Test Condition	Min	Тур	Max	Units
V _{RWM}	Reverse Working Voltage				12	V
V_{BR}	Reverse Breakdown Voltage	I _τ = 1mA	13.3			V
I R	Reverse Leakage Current	V _{RWM} = 12V			1000	nA
Vc Clamping Voltage	$I_{RWM} = 1A, t_p = 8/20 \mu s$			20	V	
	$I_{RWM} = 4A, t_p = 8/20 \mu s$			26	V	
C	Junction Capacitance	$V_R = 0V$, $f = 1MHz$		28	35	pF

Typical Characteristics

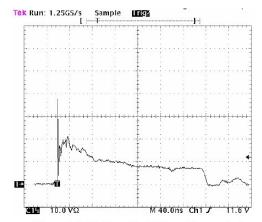
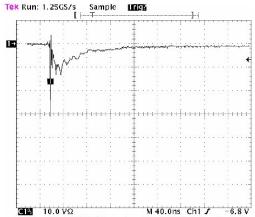


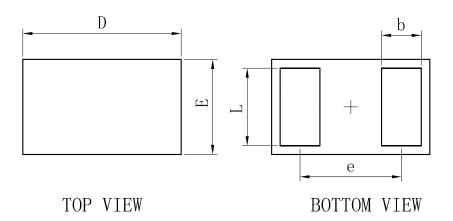
Figure 1. ESD Clamping Voltage Screenshot Positive 8 kV contact per IEC 61000-4-2



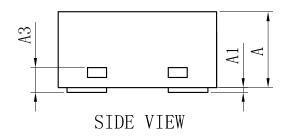
M 40.0ns Ch1 7 −6.

Figure 2. ESD Clamping Voltage Screenshot
Negative 8 kV contact per IEC 61000-4-2

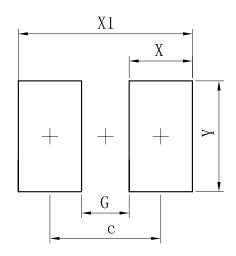
Outline And Dimensions



DFN1006-2L			
Dim	Min	Тур	Max
D	0. 95	1.00	1.05
Е	0. 55	0.60	0.65
е	-	0.64	ı
L	0.44	0.49	0. 54
b	0.20	0. 25	0.30
A	0.43	0.48	0. 53
A1	0	. 1	0.05
A3	0. 127REF.		
All Dimensions in mm			



Soledering Footprint



Dimensions	(mm)
С	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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